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File: USPT

Jul 8, 2003

DOCUMENT-IDENTIFIER: US 6589401 B1

TITLE: Apparatus for electroplating copper onto semiconductor wafer

Detailed Description Text (14):

Cup 34 is fitted with a compliant seal 58 which contacts a perimeter region of plating surface 60 of wafer 36. (The perimeter region is an area of plating surface 60 adjacent edge 62 of wafer 36.) Compliant seal 58 is typically formed of a relatively soft material preferably having a Shore A hardness in the range of 60-80. Suitable materials for compliant seal 58 include KALREZ and VITON synthetics manufactured by Dupont, and CHEMRAZ synthetic manufactured by Green, Tweed.

*Fluoropolymer*